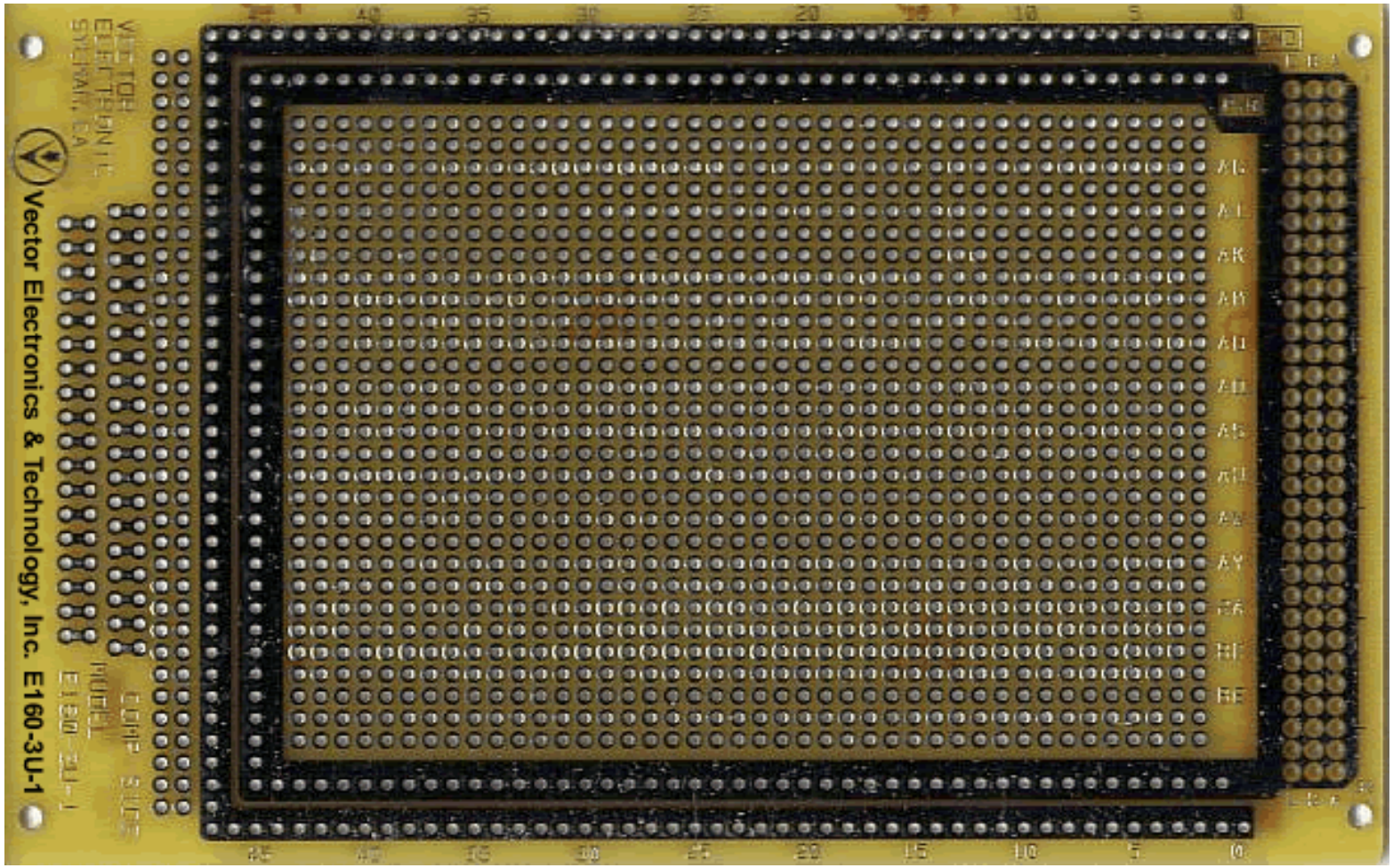
VECTOR
ELECTRONICS & TECHNOLOGY, INC.
A Fine Technology Group

3U EUROCARD PLUGBORD™ ..... PART NO. : E160-3U-1



Description :

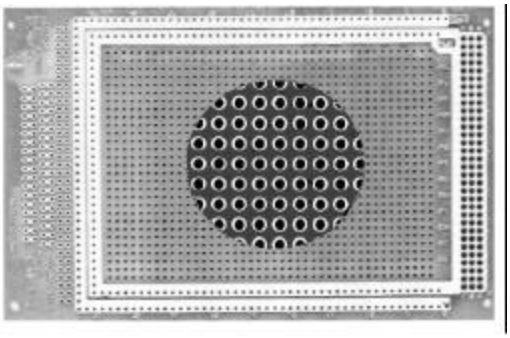
- 3U x 160 mm, Hole Dia.: 0.042", Grid: 0.100" x 0.100"
- Pad-Per-Hole
- Voltage and ground buses around board perimeter on both sides.
- Isolated solder pad around each hole on both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Plated-thru holes
- Layout paper and instructions included ..... Layout Paper(PDF)
- Row and column legends provided

Circuit Pattern :	**Pad-Per-Hole**
16 Pin DIP Capacity :	**35**
Hole Diameter :	**0.042" { 1.0668 mm }**
Grid :	**0.100" x 0.100" { 2.54mm X 2.54mm }**
Dimension { H, W, T } :	**3.94" x 6.30" x 0.062"**
Material :	**FR4 Epoxy Glass { MIL - P13949 type Gf }**
Wire-Wrap Terminals :	**T44, T46, T49, T68**
96 Pin DIN Connector :	**RE96MWR (available separately)**
Wire-Wrap Socket Pins :	**R32**
Recommended Card Cage:	**CCK 160-3U Series Card Cage { Subracks }**
NEMA Grade :	**FR4**
UL Flammability Class :	**94V - 0**

Eurocard - for 96 Pin DIN

Plugbord™

3U



E160-3U-1

3Ux160mm

Circuit Pattern:	Pad-Per-Hole
Width/Thick:	6.30"/.062"
Height:	3.94"
16-Pin DIP Capacity:	35
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Rec. Card Cage:	CCK160-3U
96-Pin Din Connector:	RE96MWR (Available Separately)
Hole Diameter:	.042"

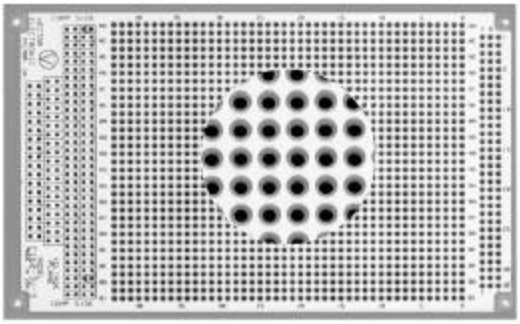
• 0.100" grid
•Voltage and ground buses around board perimeter, both sides
•Isolated solder pad around each hole, both sides
•Pad and bus surfaces solder-coated for user convenience
•For solder, Wire-Wrap or mixed wiring methods
•Layout paper and instructions included
•Row and column legends provided
•Plated-thru holes

E160-3U-2

3Ux160mm

Pad-Per-Hole

•Power & GND planes both sides

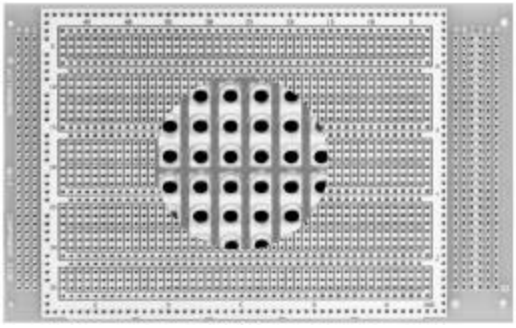


E160-3U-3

3Ux160mm

Circuit Pattern:	Voltage Ground Plane Both sides
Width/Thick:	6.30"/.062"
Height:	3.94"
16-Pin DIP Capacity:	45
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R50, R51, R52, R53
Rec. Card Cage:	CCK160-3U
96-Pin Din Connector:	RE96MWR (Available Separately)
Hole Diameter:	.055"

• 0.100" grid
•Overall voltage and ground planes on opposite board sides provide excellent shielding and power distribution
•Plane surfaces solder coated
•To simulate plated-thru holes committed to voltage or ground planes, use Vector T123 eyelets, available separately (for use without pins)
•Layout paper and instructions included
•Row and column legends provided

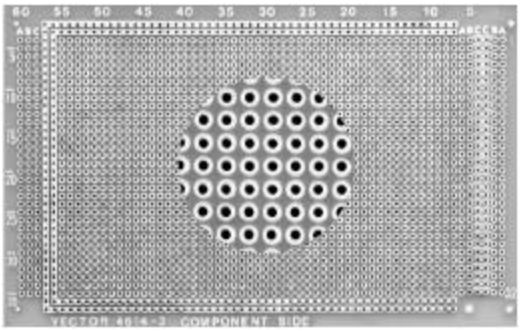


4614

3Ux160mm

Circuit Pattern:	3-Hole Solder Pad
Width/Thick:	6.30"/.062"
Height:	3.94"
16-Pin DIP Capacity:	20
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Rec. Card Cage:	CCK160-3U
96-Pin Din Connector:	RE96MWR (Available Separately)
Hole Diameter:	.042"

• 0.100" grid
•3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
•Interleaved buses on both sides, back-to-back
•Pad and bus surfaces solder-coated for user convenience
•Layout paper and instructions included
•Row and column legends provided
•Plated-thru holes



4614-3

3Ux160mm

Circuit Pattern:	Pad-Per-Hole
Width/Thick:	6.30"/.062"
Height:	3.94"
16-Pin DIP Capacity:	30
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Rec. Card Cage:	CCK160-3U
96-Pin Din Connector:	RE96MWR (Available Separately)
Hole Diameter:	.042"

• 0.100" grid
•Voltage and ground buses around board perimeter, both sides
•Pad and bus surfaces solder-coated for user convenience
•For solder, Wire-Wrap or mixed wiring methods
•Layout paper and instructions included
•Row and column legends provided
•Plated-thru holes